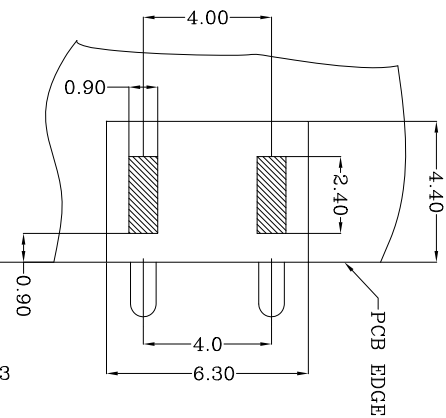
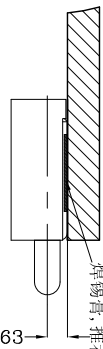


1.00 Working Stroke



PCB EDGE



Application status 2

焊锡膏, 推荐焊膏厚度为0.10mm

Application status 1
焊锡膏, 推荐焊膏厚度为0.10mm
IMPORTANT: The recommended thickness of solder paste is 0.10mm

Recommended PCB Layout & Application

Notes:
Material(材质):
Housing: LCP Color Black.
Contact: Brass
Spring : Stainless steel wire

2 Plating:
1) Body: Min 0.1um Gold plating over min. 1.4um Nickel plating (Body: 镀金0.1um Min 镀底1.4um Min)
2) Plunger: Min 0.4um Gold plating over min. 1.4um Nickel plating (Plunger: 镀金0.4um Min 镀底1.4um Min)

3 Mechanical:
Spring force: Min 20gf with 0.3mm stroke
110±30gf with 1.0mm stroke.
Total stroke(总行程): 1.40mm
Durability(寿命): 10,000 cycle min.

LDC	-
DIST	-

变更材质			
NEW			
REVISION RECORD			
APVD			
DATE			

2010/05/12	
2009/01/15	
32/	
REMOVE BURRS, BREAK SHARP EDGES R0.05 MAX DD NOT SCALE PRINT	

DIMENSIONS IN MM		MATERIAL		HT TR		FIN	
TOLERANCES UNLESS OTHER SPECIFIED		DWN Qln		APVD		REL	
0	= ±	CHK		REL		PART NUMBER	
0.0	= ±0.10	NAME		PGGD CONNECTOR 2 POSITIONS RIGHT ANGLE		100257-2	
0.000	= ±0.10	SCALE		1:1		DWG ND. 100257	
0.000	= ±	SCALE		A4		SHEET 1 OF 1	
ANGLE: ±1°		NAME		PGGD CONNECTOR 2 POSITIONS RIGHT ANGLE		REV B	
SURF TEXTURE: 32/		SCALE		1:1		SHEET 1 OF 1	
REMOVE BURRS, BREAK SHARP EDGES R0.05 MAX DD NOT SCALE PRINT		SCALE		A4		REV B	

三佐株式会社

USED DN

4

3

2

1

A

B

C

D